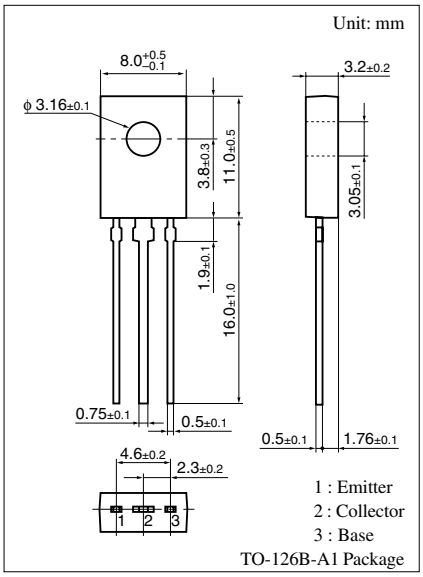
2SC2497, 2SC2497A

Silicon NPN epitaxial planar type

For low-frequency power amplification
Complementary to 2SA1096 and 2SA1096A



■ Features

- High collector to emitter voltage V_{CEO}
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_C = 25°C$

Parameter		Symbol	Rating	Unit
Collector to base voltage		V_{CBO}	70	V
Collector to emitter voltage	2SC2497	V_{CEO}	50	V
	2SC2497A		60	
Emitter to base voltage		V_{EBO}	5	V
Peak collector current		I_{CP}	3	A
Collector current		I_C	1.5	A
Collector power dissipation		P_C	1.2 *1	W
			5 *2	
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

Note) ∗1: Without heat sink
∗2: With a 100 × 100 × 2 mm A1 heat sink

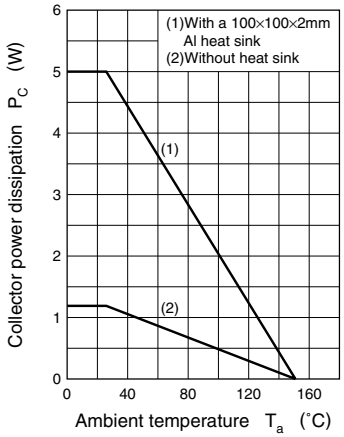
■ Electrical Characteristics $T_C = 25°C$

Parameter		Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current		I_{CBO}	V_{CB} = 20 V, I_E = 0			1	µA
		I_{CEO}	V_{CE} = 10 V, I_B = 0			100	µA
Emitter cutoff current		I_{EBO}	V_{EB} = 5 V, I_C = 0			10	µA
Collector to base voltage		V_{CBO}	I_C = 1 mA, I_E = 0	70			V
Collector to emitter voltage	2SC2497	V_{CEO}	I_C = 2 mA, I_B = 0	50			V
	2SC2497A			60			
Forward current transfer ratio *		h_{FE}	V_{CE} = 5 V, I_C = 1 A	80		220	
Collector to emitter saturation voltage		$V_{CE(sat)}$	I_C = 1.5 A, I_B = 0.15 A			1	V
Base to emitter saturation voltage		$V_{BE(sat)}$	I_C = 1.5 A, I_B = 0.15 A			1.5	V
Transition frequency		f_T	V_{CB} = 5 V, I_E = − 0.5 A, f = 200 MHz		150		MHz
Collector output capacitance		C_{ob}	V_{CB} = 20 V, I_E = 0, f = 1 MHz		35		pF

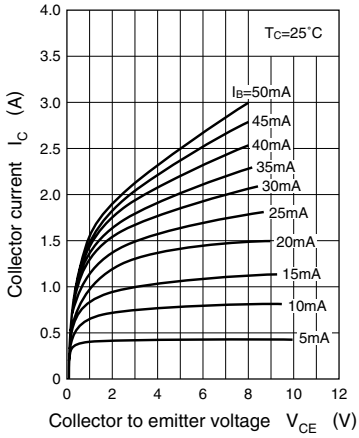
Note) ∗: Rank classification

Rank	R	S
h_{FE}	80 to 160	120 to 220

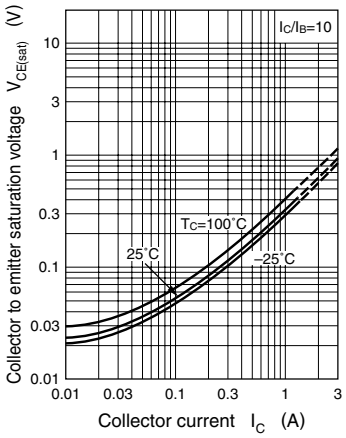
P_C — T_a



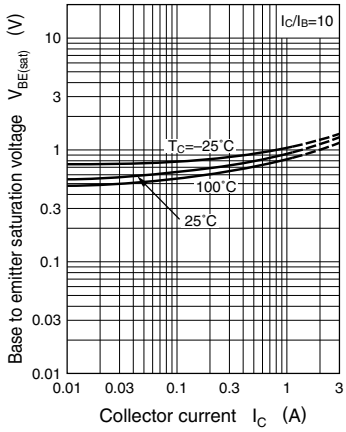
I_C — V_{CE}



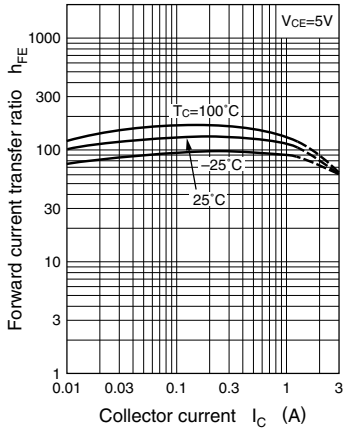
$V_{CE(sat)}$ — I_C



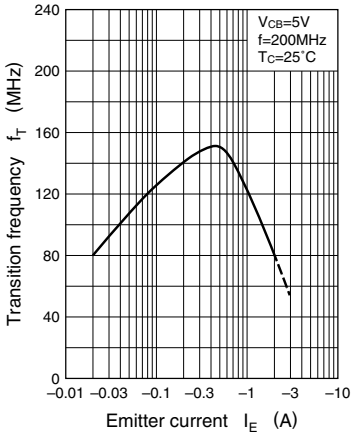
$V_{BE(sat)}$ — I_C



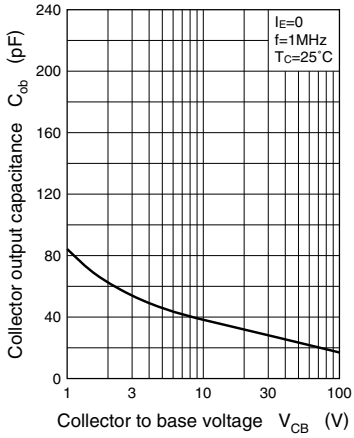
h_{FE} — I_C



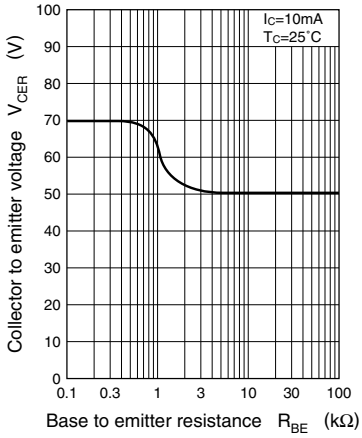
f_T — I_E



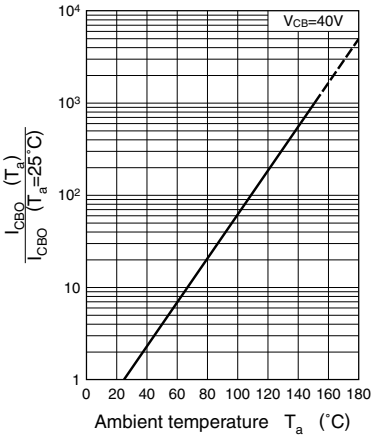
C_{ob} — V_{CB}



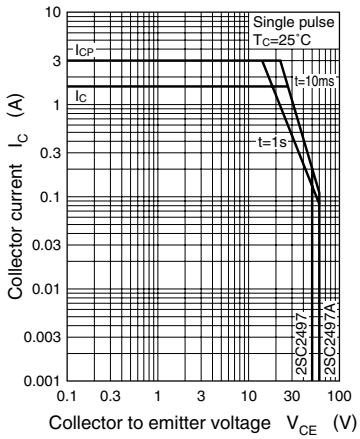
V_{CER} — R_{BE}



I_{CBO} — T_a



Area of safe operation (ASO)



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